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(54) Title: MULTIPLE LAYER POLYMER INTERLAYERS HAVING AN EMBOSSED SURFACE

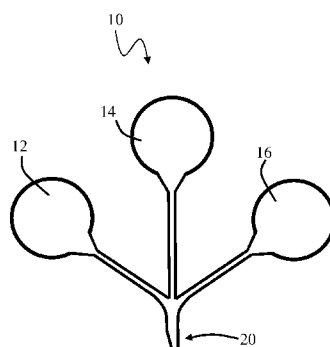


Fig. 1

(57) Abstract: The present invention provides multiple layer interlayers having a relatively soft inner layer and relatively stiff outer layers that can be laminated without unacceptable optical distortion and used in various multiple layer glass panel type applications. Multiple layer interlayers of the present invention have surface topography that is formed by embossing the exposed surface of the interlayer, or individual layers of the multiple layer interlayer, after formation of the interlayer or layers. The embossing process is carried out under temperature conditions that prevent the transfer of the embossing to inner layers of the interlayer. By precisely controlling the embossing of the interlayer, lamination of the interlayer with a rigid substrate does not lead to unacceptable optical distortion caused by the transfer of the surface topography through outer, stiffer layers into softer, internal layers of the interlayer.

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